



P-Channel 20-V (D-S) MOSFET with Schottky Diode

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	Q _g (Typ.)			
- 20	$0.070 \text{ at V}_{GS} = -5.0 \text{ V}$	- 5.0	4.5 nC			
	0.105 at V _{GS} = - 2.5 V	- 4.2	4.5110			

SCHOTTKY PRODUCT SUMMARY					
V _{KA} (V)	V _f (V) Diode Forward Voltage	I _F (A) ^a			
20	0.45 at 1 A	2			

FEATURES

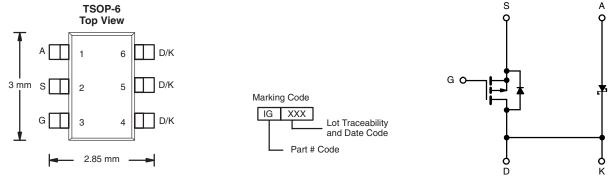
- Halogen-free According to IEC 61249-2-21 Definition
- LITTLE FOOT® Plus Schottky Power MOSFET
- Compliant to RoHS Directive 2002/95/EC



ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- HDD
 - DC-DC Converter
- · Asynchronous Rectification



Ordering Information: Si3879DV-T1-E3 (Lead (Pb)-free)

Si3879DV-T1-GE3 (Lead (Pb)-free and Halogen-free)

P-Channel MOSFET

Parameter		Symbol	Limit	Unit
Drain-Source Voltage (MOSFET)		V _{DS}	- 20	
Reverse Voltage (Schottky)		V _{KA}	20	V
Gate-Source Voltage (MOSFET)		V _{GS}	± 12	
	T _C = 25 °C		- 5.0	
Continuous Drain Current (T. – 150 °C) (MOSEET)	T _C = 70 °C] [- 4.0	
Continuous Drain Current (T _J = 150 °C) (MOSFET)	T _A = 25 °C	l _D	- 4.0 ^{b, c}	
	T _A = 70 °C]	- 3.0 ^{b, c}	
Pulsed Drain Current (MOSFET)		I _{DM}	- 20	Α
Continuous Source-Drain Diode Current	T _C = 25 °C	- I _S	- 2.7	
(MOSFET Diode Conduction)	T _A = 25 °C		- 1.6 ^{b, c}	
Average Forward Current (Schottky)		I _F	2 ^b	
Pulsed Forward Current (Schottky)		I _{FM}	5	
	T _C = 25 °C		3.3	
Maximum Power Dissipation (MOSFET)	T _C = 70 °C] [2.1	
Maximum Fower Dissipation (MOSFET)	T _A = 25 °C] [2.0 ^{b, c}	
	T _A = 70 °C	P _D	1.2 ^{b, c}	w
	T _C = 25 °C	' D	1.9	vv
Maximum Power Discipation (Schottky)	T _C = 70 °C		1.2	
Maximum Power Dissipation (Schottky)	T _A = 25 °C		1.3 ^{b, c}	
	T _A = 70 °C		0.9 ^{b, c}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C	

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THERMAL RESISTANCE RATINGS								
Parameter		Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient (MOSFET) ^{b, d}	t ≤ 5 s	R_{thJA}	51	62.5				
Maximum Junction-to-Foot (Drain) (MOSFET)	Steady State	R_{thJF}	30	37	°C/W			
Maximum Junction-to-Ambient (Schottky)b, e	t ≤ 5 s	R_{thJA}	73	90	C/VV			
Maximum Junction-to-Foot (Drain) (Schottky)	Steady State	R_{thJF}	50	65				

- Notes: a. Based on T_C = 25 °C. b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under Steady State conditions is 105 °C/W.
 e. Maximum under Steady State conditions is 125 °C/W.

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	1					I.
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V, I}_{D} = -250 \mu\text{A}$	- 20			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 20		m\//°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μΑ		3		mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.6		- 1.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			- 1 - 10	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le 5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 8			Α
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -4.5 \text{ V, } I_D = -3.5 \text{ A}$ $V_{GS} = -2.5 \text{ V, } I_D = -3.0 \text{ A}$		0.058 0.085	0.070 0.105	Ω
Forward Transconductancea	9 _{fs}	V _{DS} = - 10 V, I _D = - 3.5 A		10		S
Dynamic ^b			I			L
Input Capacitance	C _{iss}			480		
Output Capacitance	C _{oss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		132		pF
Reverse Transfer Capacitance	C _{rss}			55		
Total Gate Charge	Qq	$V_{DS} = -10 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -5.0 \text{ A}$		9.7	14.5	
0.1.0		10 10 10 10 10 10 10 10 10 10 10 10 10 1		4.5	7	nC
Gate-Source Charge	Q _{gs}	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -4.5 \text{ A}$		1.0		
Gate-Drain Charge	Q _{gd}	(, ,) ()		1.0		
Gate Resistance	R _g	f = 1 MHz		7.5	40	Ω
Turn-On Delay Time	t _{d(on)}	V 40V D 000		6	10	
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_L = 2.0 \Omega$		54	85	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -5.0 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		19	30	1
Fall Time	t _f			8	15	ns
Turn-On Delay Time	t _{d(on)}			26	40	
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_{L} = 2.0 \Omega$		80	120	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -5.0 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		20	30	
Fall Time	t _f			10	15	





SPECIFICATIONS $T_J = 25$ °C, unless otherwise noted								
Parameter	Symbol	Test Conditions		Тур.	Max.	Unit		
Drain-Source Body Diode Characteristics								
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 2.7	Α		
Pulse Diode Forward Current	I _{SM}				- 20	^		
Body Diode Voltage	V_{SD}	I _S = - 1.0 A, V _{GS} = 0 V		- 0.75	- 1.2	V		
Body Diode Reverse Recovery Time	t _{rr}			25	40	ns		
Body Diode Reverse Recovery Charge	Q_{rr}	$I_F = -3.5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		12	20	nC		
Reverse Recovery Fall Time	t _a			9		- ns		
Reverse Recovery Rise Time	t _b			16				

Notes:

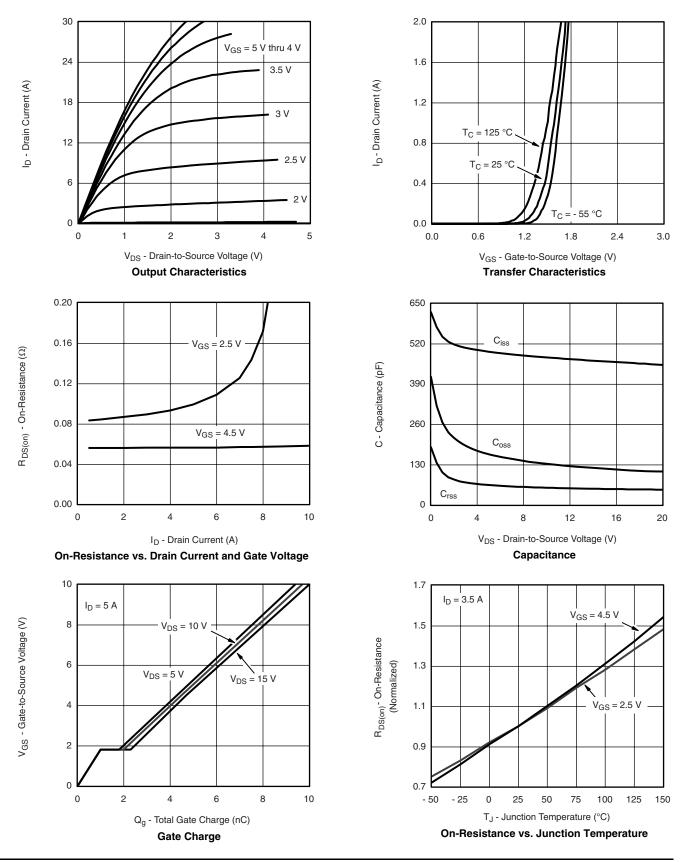
- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

SCHOTTKY SPECIFICATIONS								
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Forward Voltage Drop	V _F	I _F = 1 A		0.41	0.45	V		
	v _F	I _F = 1 A, T _J = 125 °C		0.36	0.41			
		V _R = 5 V		0.015	0.08			
		V _R = 5 V, T _J = 85 °C		0.50	5.00			
Maximum Reverse Leakage Current	I _{rm}	I_{rm} $V_{R} = 20 \text{ V}$ 0.0	0.02	0.10	mA			
		$V_R = 20 \text{ V}, T_J = 85 ^{\circ}\text{C}$		0.7	7.00			
		V _R = 20 V, T _J = 125 °C		5	50			
Junction Capacitance	C _T	V _R = 10 V		60		pF		

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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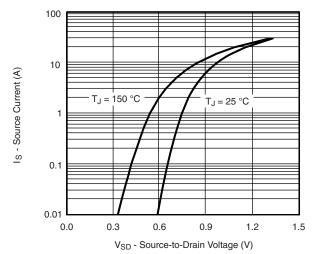
MOSFET TYPICAL CHARACTERISTICS $T_A = 25~^{\circ}C$, unless otherwise noted



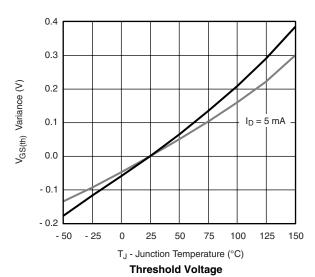


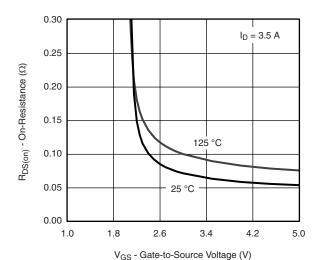


MOSFET TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted

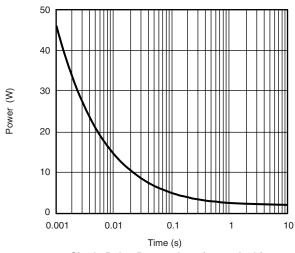


Soure-Drain Diode Forward Voltage

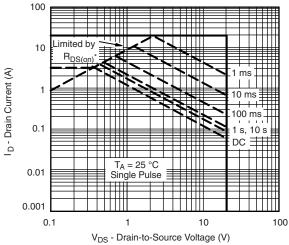




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

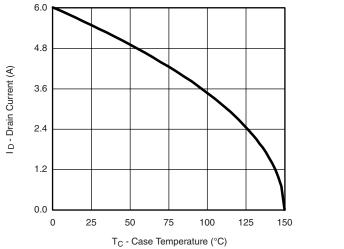


* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

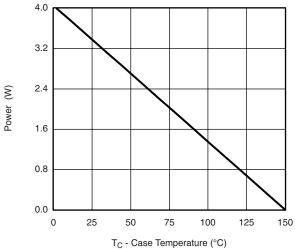
Safe Operating Area, Junction-to-Case

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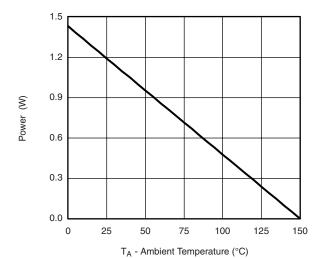
MOSFET TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted



Current Derating*



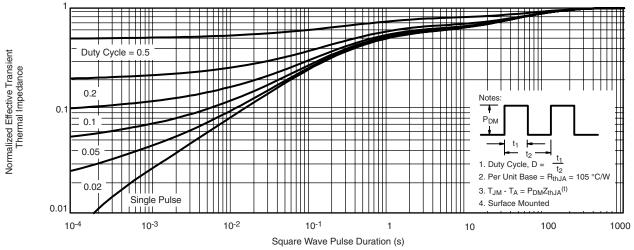
Power Derating, Junction-to-Foot



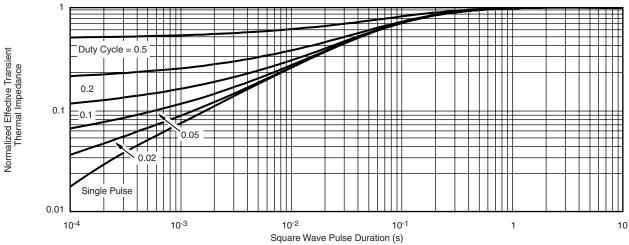
Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

MOSFET TYPICAL CHARACTERISTICS $T_A = 25$ °C, unless otherwise noted



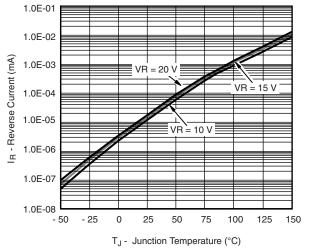
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

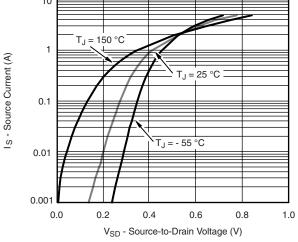


SCHOTTKY TYPICAL CHARACTERISTICS $T_A = 25~^{\circ}C$, unless otherwise noted

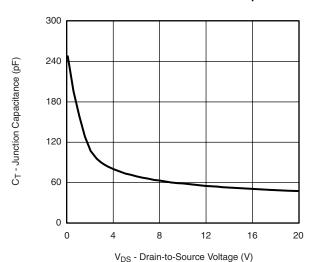


Reverse Current vs. Junction Temperature

Capacitance



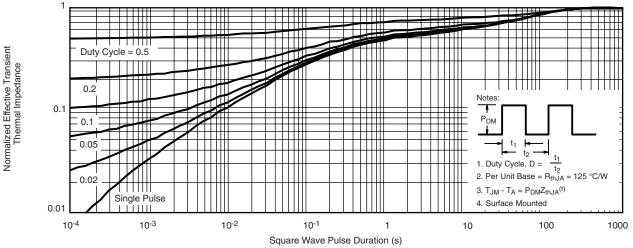
Forward Diode Voltage



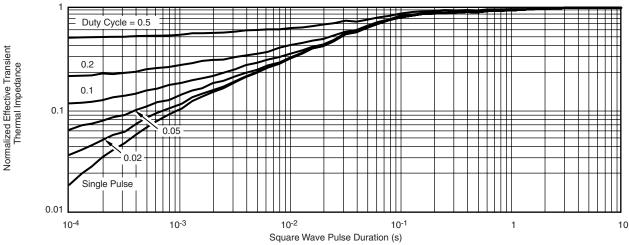
24 18 18 12 6 0 0.001 0.01 0.1 1 1 1 Time (s)

Single Pulse Power, Junction-to-Ambient

SCHOTTKY TYPICAL CHARACTERISTICS $T_A = 25~^{\circ}C$, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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